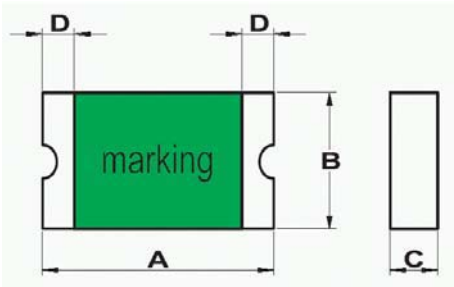


Construction and Dimension:

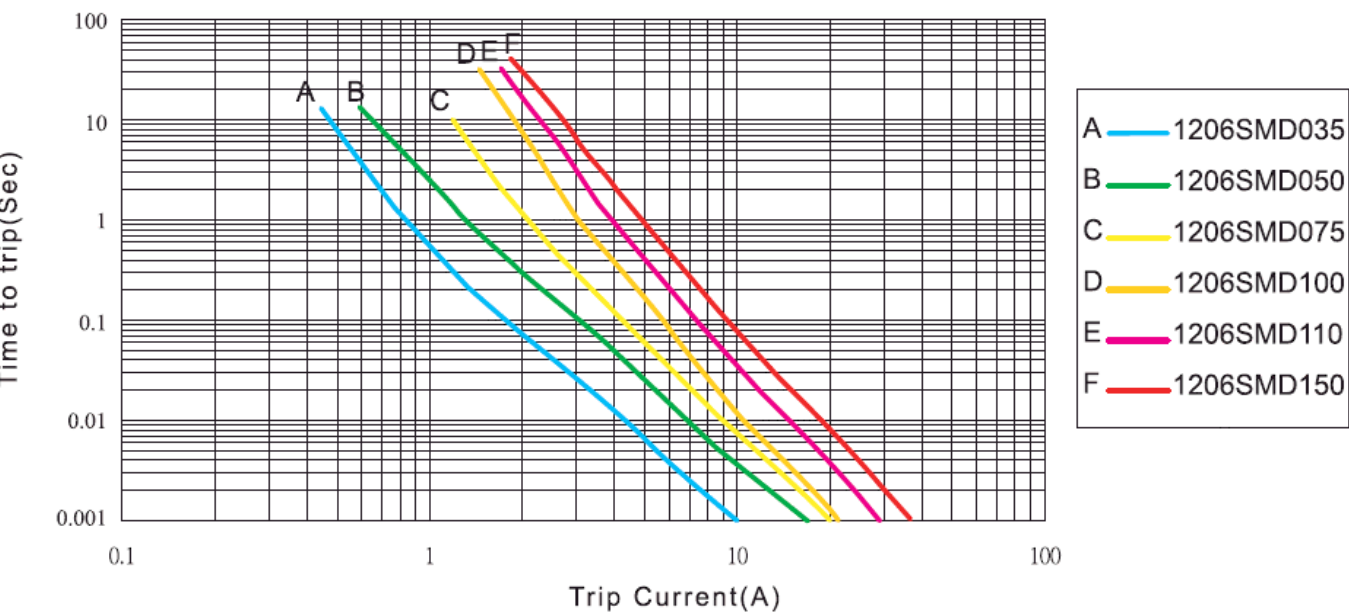


Model	A		B		C		D	
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
1206SMD035	3.00	3.50	1.50	1.80	0.30	2.00	0.20	0.80
1206SMD050	3.00	3.50	1.50	1.80	0.30	2.00	0.20	0.80
1206SMD075	3.00	3.50	1.50	1.80	0.30	2.00	0.20	0.80
1206SMD100	3.00	3.50	1.50	1.80	0.60	2.00	0.20	0.80
1206SMD110	3.00	3.50	1.50	1.80	0.60	2.00	0.20	0.80
1206SMD150	3.00	3.50	1.50	1.80	0.60	2.00	0.20	0.80

Electrical Characteristics at 23⁰C

Model	V max (Volts)	I max (Amps)	I hold (Amps)	I trip (Amps)	R min (Ω)	R max (Ω)	R1 max (Ω)	P (d) (Watts)
1206SMD035	6.0	40	0.35	0.70	0.20	0.75	1.60	0.6
1206SMD050	6.0	40	0.50	1.00	0.15	0.40	1.20	0.6
1206SMD075	6.0	40	0.75	1.50	0.07	0.20	0.75	0.6
1206SMD100	6.0	40	1.00	2.00	0.04	0.12	0.30	0.6
1206SMD110	6.0	40	1.10	2.20	0.04	0.12	0.30	0.6
1206SMD150	6.0	40	1.50	3.00	0.02	0.08	0.20	0.8

Construction and Dimension:



Thermal Derating Chart

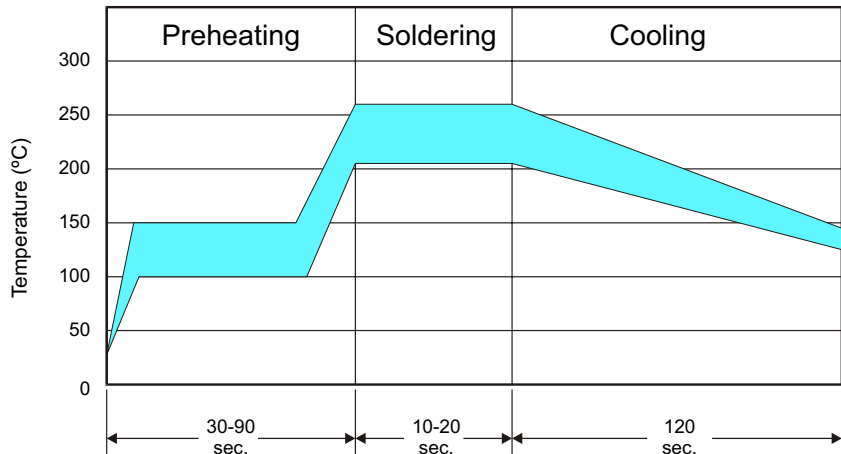
TEMP(°C)	- 40	- 20	0	23	40	50	60	70	85
1206SMD035	0.50	0.46	0.40	0.35	0.28	0.24	0.22	0.205	0.19
1206SMD050	0.77	0.69	0.58	0.50	0.43	0.39	0.34	0.31	0.25
1206SMD075	1.07	0.96	0.84	0.75	0.65	0.60	0.51	0.47	0.40
1206SMD100	1.51	1.35	1.16	1.00	0.87	0.80	0.71	0.65	0.54
1206SMD110	1.55	1.40	1.20	1.10	0.90	0.85	0.75	0.70	0.58
1206SMD150	2.17	1.95	1.75	1.50	1.34	1.21	1.07	0.99	0.82

Product Packing

Type	Series	Packing type	Quantity	
SMD	0805SMD	Reel Packahing	3000	Reel
	1206SMD		3000	
	1812SMD		1500	
	2920SMD		2000	

Reflow

- The recommended reflow profile is shown as the figure at right hand side.
- A maximum solder paste of thickness 0.25mm is recommended.
- Hot air, infra-red, vapor phase reflowing are recommended.



WARNING:

- Devices may not meet specifications if reflow temperatures exceed the recommended profile.
- Operation beyond maximum ratings or improper use may result in device damage and possible electrical arcing, flaming or explosion.
- The devices may not meet specified ratings if storage conditions exceeded 40°C and 70% relative humidity.
- The devices are intended to protect against occasional over-current or over-temperature fault conditions and should not be used when there are repeated fault conditions or prolonged trip events.
- The devices should not be placed under pressure or installed in spaces that would prevent thermal expansion, due to any prohibition of thermal expansion of the devices might result improper protection of fault conditions.
- reserves the right to change any information or specification within this data book without notice.

PPTC RESETTABLE FUSE

Definition of Electrical Characteristics

- ☐ $V_{\max}$: Maximum voltage the device can withand without damage at rated current.
- ☐ $I_{\max}$: Maximum fault current the device can withand without damage at rated voltage.
- ☐ I_{hold} : Hold current; Maximum current at which the device will not trip in 23°C still air.
- ☐ I_{trip} : Trip current; Minimum current at which the device will trip in 23°C still air.
- ☐ $R_{\min}$: Minimum device resistance in initial state at 23°C.
- ☐ $R_{\max}$: Maximum device resistance in initial state at 23°C.
- ☐ $R_{1\max}$: Maximum device resistance at 23°C measured 1 hours after tripping.
- ☐ $P(d)$: Maximum power dissipated from device when in the tripped state in 23°C still air.

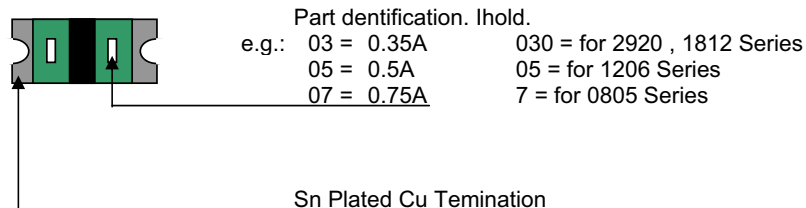
Test and Environmental Characteristics

Items	Specification/Condition	Accept Criteria
Initial resistance	In still air at 23°C	$R_{\min} \leq R \leq R_{\max}$
Time to trip	At specified current, $V_{\max}$ at 23°C	Refer to time-to-trip chart
Hold current	30 min., at I_{hold}	No trip
Trip endurance	$V_{\max}$, $I_{\max}$, 100 cycles	No arcing or burning
Trip aging	$V_{\max}$, 48 hours	No arcing or burning
Max.device surface temp.	In tripped state	125°C max.
Passive aging	85°C, 1000 hours	± 10% typical resistance change
Humidity aging	85°C, 85% RH, 1000 hours	± 10% typical resistance change
Thermal shock	85°C/-40°C, 10 times	+5 ~ -20% typical resistance change

Ordering Information

Size ——— 1206 SMD 050
Surface Mount ———
Hold Current I_{hold} ———
035- 150 (0.35A - 1.5A)

Part Marking

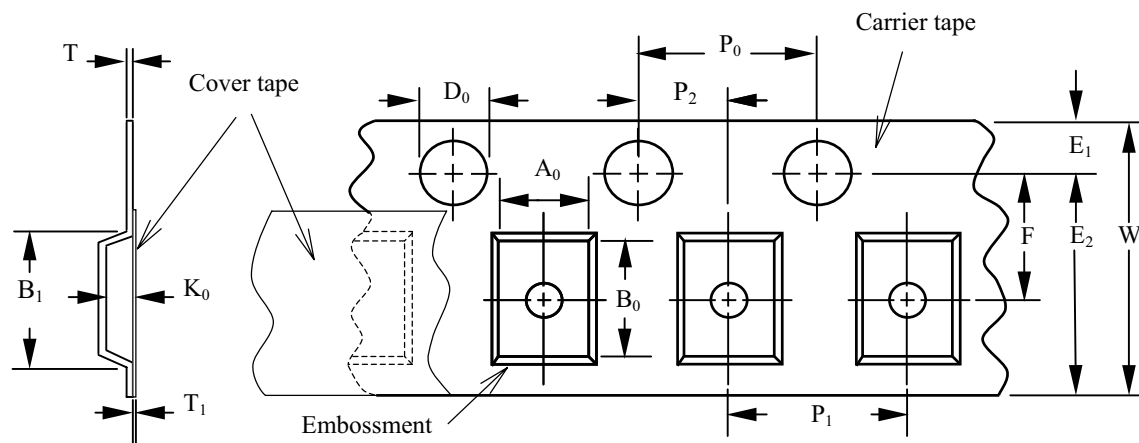


Note: All drawing are not in scale and layout may vary.
All oarts dimension is in millimeter unless otherwise specified.
Teminal material is Tin (Sn) plated Copper (Cu)

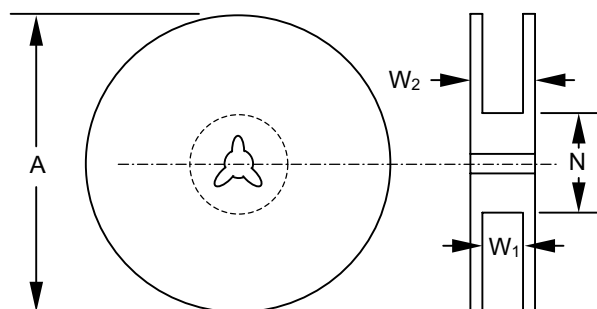
Agency Approval: UL File Number: Pending
 c-UL File Number: Pending
 TUV File Number: Pending

Tape & Reel Packaging Specification per EIA481-1

Type: 1206SMD



Parameter as EIA481-1	Dimensions (mm)
W	8.00 ± 0.30
P ₀	4.00 ± 0.10
P ₁	4.00 ± 0.10
P ₂	2.00 ± 0.05
A ₀	1.88 ± 0.10
B ₀	3.50 ± 0.10
B ₁ max.	4.35
D ₀	1.50 +0.10/-0.00
F	3.50 ± 0.05
E ₁	1.75 ± 0.10
E ₂ min.	6.25
T max.	0.6
T ₁ max.	0.1
K ₀	0.90 ± 0.10



Parameter as EIA481-1	Dimensions (mm)
A max.	185
N min.	50
W ₁	8.4 +1.5/-0.0
W ₂ max.	14.4